

Publikationen

(2020): Wafer composite and method for producing semiconductor components.

(2020): Silicon carbide semiconductor device and a method for forming a silicon carbide semiconductor device.

(2019): Semiconductor devices and methods for forming semiconductor devices.

(2019): Method of manufacturing semiconductor devices by bonding a semiconductor disk on a base substrate, composite wafer and semiconductor device.

(2017): Method for manufacturing a composite wafer having a graphite core, and composite wafer having a graphite core.

(2016): Composite wafer for bonding and encapsulation of a SiC-based functional layer.

(2015): Method for manufacturing a composite wafer having a graphite core, and composite wafer having a graphite core.

(2015): Compound structure and method for forming a compound structure.

(2014): Method for manufacturing a composite wafer having a graphite core, and composite wafer having a graphite core.